

# 2SK1809

## Silicon N Channel MOS FET

REJ03G0976-0200

(Previous: ADE-208-1323)

Rev.2.00 Sep 07, 2005

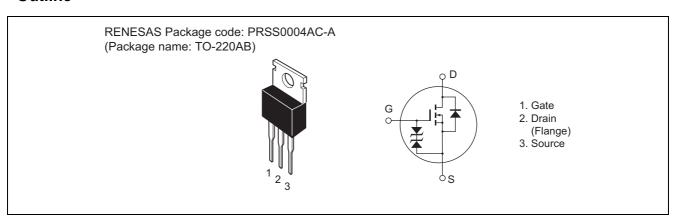
## **Application**

High speed power switching

### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter

### **Outline**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	600	V
Gate to source voltage	$V_{GSS}$	±30	V
Drain current	I <sub>D</sub>	5	А
Drain peak current	I <sub>D(pulse)</sub> *1	20	А
Body to drain diode reverse drain current	I <sub>DR</sub>	5	А
Channel dissipation	Pch <sup>*2</sup>	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

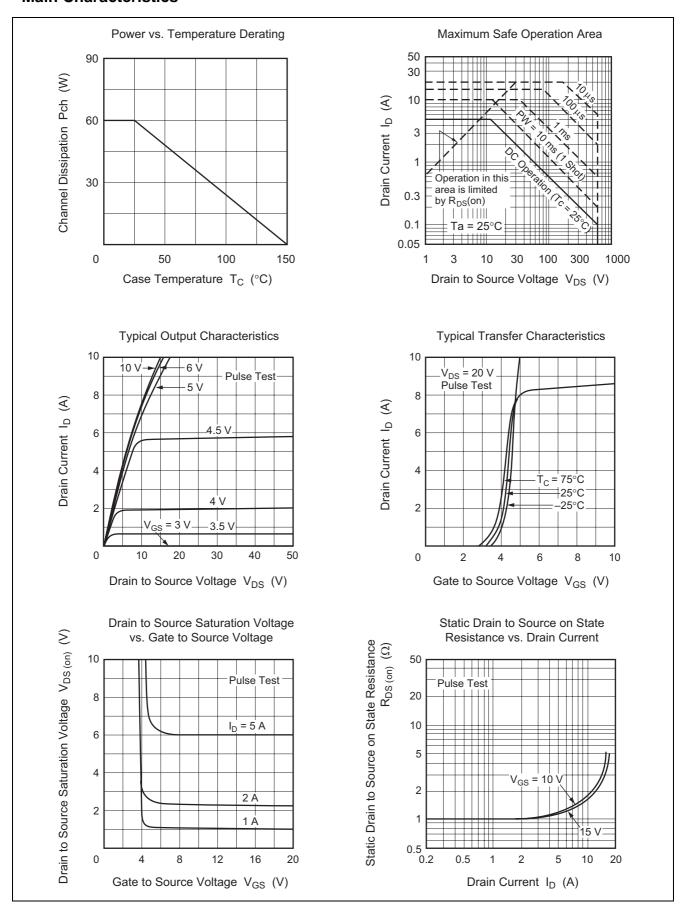
## **Electrical Characteristics**

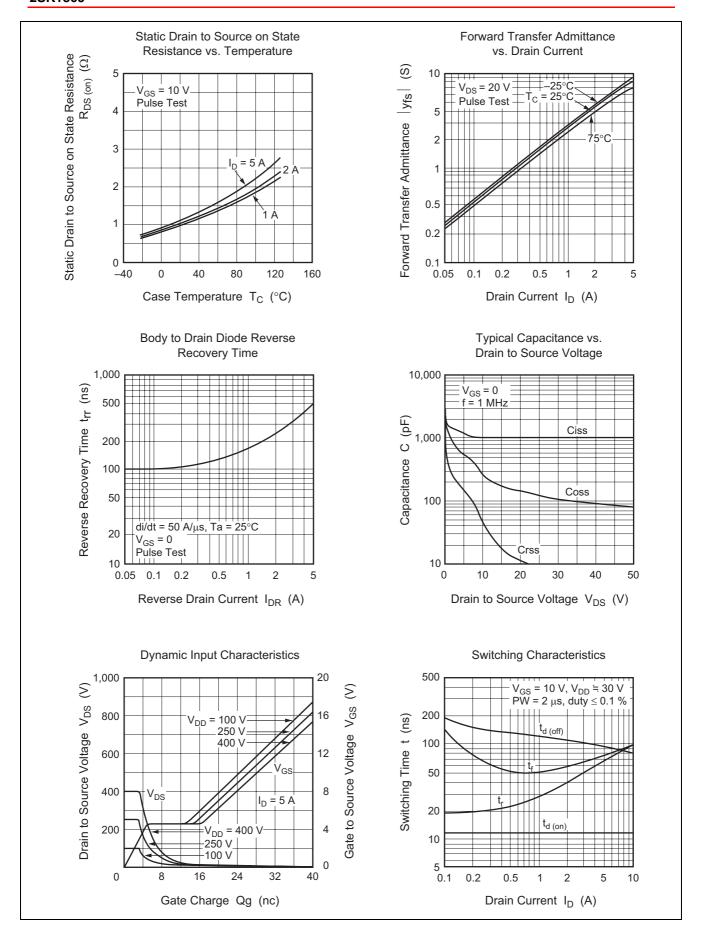
 $(Ta = 25^{\circ}C)$ 

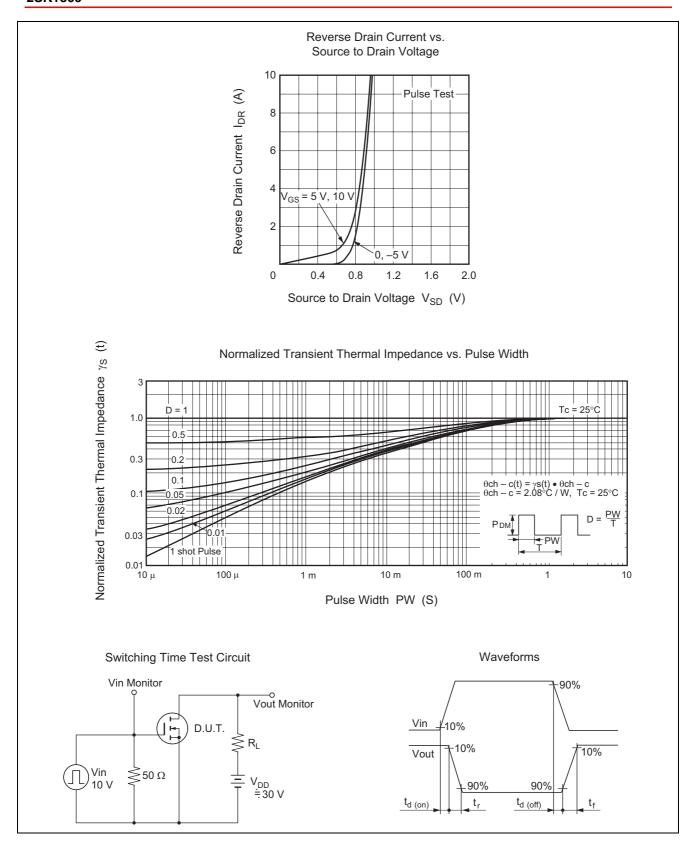
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	-	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$	
Static drain to source on state resistance	R <sub>DS(on)</sub>	_	1.1	1.5	Ω	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V*}^3$	
Forward transfer admittance	y <sub>fs</sub>	3.0	5.0	_	S	$I_D = 2.5 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$	
Input capacitance	Ciss	_	1000	-	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$	
Output capacitance	Coss	_	250	_	pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	45	_	pF		
Turn-on delay time	t <sub>d(on)</sub>	_	12	_	ns	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V},$ $R_L = 12 \Omega$	
Rise time	t <sub>r</sub>	_	45	_	ns		
Turn-off delay time	t <sub>d(off)</sub>	_	105	_	ns		
Fall time	t <sub>f</sub>	_	55	_	ns	]	
Body to drain diode forward voltage	$V_{DF}$	_	0.9	_	V	$I_F = 5 A, V_{GS} = 0$	
Body to drain diode reverse recovery time	t <sub>rr</sub>	_	500		ns	$I_F = 5 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$	

Note: 3. Pulse Test

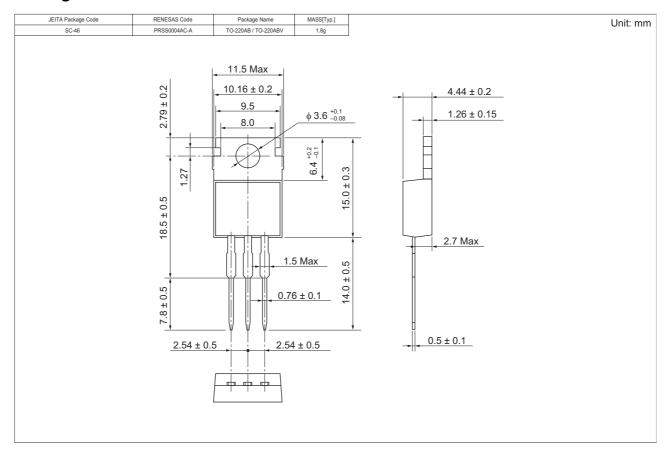
### **Main Characteristics**







## **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
2SK1809-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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